

# **FAN STAND STRUCTURE FOR CENTRAL PROCESSING UNIT**

## **BACKGROUND OF THE INVENTION**

### **(a) Field of the Invention**

5        The invention relates to a fan stand structure for central processing unit (CPU), and more particularly, to a stand structure for fixing a heat dissipating fan of a CPU, in that the stand structure comprises a lower rear panel and an upper frame.

### **(b) Description of the Prior Art**

10        With reference to FIG. 1A, a prior central processing unit (CPU) heat dissipating structure a is generally mounted on a CPU base c using a fastening apparatus b, and is located closely to cooling fins a1 and a CPU c1. Heat produced by the CPU c1 is transmitted to the cooling fins a1, and is overblown by the heat dissipating fan a2 situated above. The

15        fastening apparatus c is mostly devised with fastening openings b1 at two ends thereof for fixing with fastening sections c2 at two sides of the CPU base c. This prior structure indeed offers practical conveniences and satisfactory stability. However, thermal energy is relatively increased along with faster and faster CPU speeds, meaning that a

20        volume of the heat dissipating structure is inevitably enlarged in order to

provide better heat dissipating effects. It is to be noted that the heat dissipating fan a2 is fastened at the CPU base c, and vibrations of the heat dissipating fan a2 are likely to cause undesired direct effects on the CPU c1. In addition, dimensions of the CPU base c are manufactured  
5 according to dimensions of the CPU c1, and are usually in certain specifications. When dimensions of the heat dissipating structure a are larger than those of the CPU base c, fastening the heat dissipating structure a using the fastening apparatus b becomes rather difficult, not to mention that breakage of the fastening sections c2 is easily incurred  
10 during replacement to further cause damages of the CPU base c.

To overcome the aforesaid shortcomings, another type of stand d is available for supporting a larger heat dissipating structure a as shown in FIG. 1B. A stand d being a hollow square in shape is disposed at a periphery of the CPU base c, and has supporting frames d1 at two side  
15 edges thereof. An upper portion of each supporting frame d1 is provided with fastening openings d11, which work in conjunction with corresponding fastening sections a31 at a plastic housing a3 at the heat dissipating structure 1, so as to mount the entire heat dissipating structure a above the CPU c1 and to facilitate disassembly and  
20 assembly of the heat dissipating structure a while also providing

enhanced stability. Nevertheless, such fixed stand d is irreplaceable, and therefore it cannot be replaced once the stand d is damaged. It is essential that this prior structure be advanced.

## **SUMMARY OF THE INVENTION**

5 In the view of the aforesaid shortcomings of the prior inventions, the primary object of the invention is to provide a fan stand structure for CPU, in that the fan stand has simple installation and replacement processes as well as excellent stability.

To accomplish the aforesaid object, a fan stand structure for CPU  
10 according to the invention comprises an upper frame, a lower rear panel, expanding nail assemblies and positioning screw assemblies. For corresponding with orifices at a periphery of a CPU base of a motherboard, the lower rear panel has positioning holes at four corners thereof and screw holes at two sides thereof. The lower rear panel is  
15 placed at a reverse side of the CPU base of the motherboard, and the upper frame is installed at an obverse side of the CPU base of the motherboard. The upper frame has four supporting arms, and appears as a hollow square shape when viewed from top. For corresponding with the lower rear panel, the upper frame further has positioning holes  
20 at four corners thereof and screw holes at two sides thereof.

According to the aforesaid structure, the expanding nail assemblies are inserted through the positioning holes at the four corners of the lower rear panel to become fastened with the upper frame, or the positioning screw assemblies are inserted through the screw holes of the lower rear  
5 panel to become fastened with the upper frame. By clamping the motherboard with the upper frame and the lower rear panel, the entire fan stand structure is firmed located at appropriate positions at a periphery of the CPU base, thereby providing simple installation and replacement processes. In addition, points of force application are  
10 distributed at the periphery, and therefore vibrations caused by a heat dissipating fan are evenly transmitted to the motherboard to prevent the heat dissipating fan from imposing direct effects on the CPU.

#### **BRIEF DESCRIPTION OF THE DRAWINGS**

FIG. 1A shows a schematic view of a prior heat dissipating structure  
15 using a fastening apparatus.

FIG. 1B shows a schematic view of a prior heat dissipating structure using a stand for locating purposes.

FIG. 2 shows an exploded elevational view illustrating a stand structure according to the invention.

20 FIG. 3 shows an exploded view illustrating an embodiment according

to the invention.

FIG. 4 shows an elevation view illustrating an embodiment according to the invention.

FIG. 5 shows an installation embodiment according to the invention  
5 with a heat dissipating structure.

### **DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS**

To better understand the structure, devices and characteristics of the invention, detailed descriptions of a preferred embodiment shall be given with the accompanying drawings below.

10 With reference to FIG. 2 showing a fan stand structure for central processing unit (CPU), a stand structure 1 comprises an upper frame 10, a lower rear panel 20, expanding nail assemblies 30 and positioning screw assemblies 40. The stand structure 1 is an integral formed by plastic extrusion.

15 The upper frame 10 appears as a hollow square when viewed from top, and has four supporting arms 11 at two sides thereof. Each supporting arm 11 has a fastening opening 11a at an upper portion thereof. For corresponding with the lower rear panel 20, the upper frame 10 further has positioning holes 12 at four corners thereof, and screw holes 13 at  
20 center portions of two sides thereof.

The lower rear panel 20 is a plate-structure at an obverse side thereof, and has a plurality of reinforcement ribs 21 at a reverse side thereof in order to minimize weight. For corresponding with orifices 2b at a base 2a of a motherboard 2, the lower panel 20 further has four positioning  
5 holes 22 at four corners thereof and two screw holes 23 at center portions of two sides thereof.

Each expanding nail assembly 30 is consisted of a main expanding nail 31 and an insertion nail 32. The main expanding nails 31 are first inserted through the positioning holes 12 of the upper frame 10 and the  
10 positioning holes 22 of the lower rear panel 20, and then the insertion nails 32 are inserted into the main expanding nails 31, so as to have the main expanding nails 31 expand within the positioning holes 22 of the lower rear panel 20.

Each positioning screw assembly 40 is consisted of a hexagonal nut  
15 41 and a screw 42. The hexagonal nuts 41 are placed in the screw holes 23 of the lower rear panel 20, and the screws 42 are inserted through the screw holes 13 of the upper frame 10 to become screwed and fastened with the hexagonal nuts 41.

Referring to FIGS. 3 and 4, to mount the stand structure 1 to the  
20 motherboard 2, an obverse side of the lower rear panel 20 is leaned

against a reverse side of the base 2a, and the positioning holes 22 and the screw holes 23 are aligned with the orifices 2b at the motherboard 2. Next, a reverse side of the upper frame 10 is leaned against an obverse side of the motherboard 2, and the positioning holes 12 and the screw holes 13 are aligned with the orifices 2b at the motherboard 2. The expanding nail assemblies 30 and the positioning screw assemblies 40 are inserted through the positioning holes 12 and 22, and the screw openings 13 and 23, thereby clamping the motherboard 2 at a center portion of the stand structure 1. Referring to FIG. 5 showing an installation embodiment according to the invention with a heat dissipating structure 3, the heat dissipating structure 3 is fastened with the fastening openings 11a at the supporting arms 11 of the upper frame 10 using a plastic frame 3a.

Conclusive from the above, the fan stand structure for CPU according to the invention utilizes the upper frame and the lower rear panel to clamp and position the motherboard. The invention not only locates the fan stand for simply installation and replacement purposes, but also provides overall stability. It is of course to be understood that the embodiment described herein is merely illustrative of the principles of the invention and that a wide variety of modifications thereto may be

effected by persons skilled in the art without departing from the spirit and scope of the invention as set forth in the following claims.